1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716

General Description

The AUR9716 is a high efficiency step-down DC-DC voltage converter. The chip operation is optimized by peak-current mode architecture with built-in synchronous power MOS switchers. It is automatically switching between the normal PWM mode and LDO mode to offer improved system power efficiency covering a wide range of loading conditions.

Switching frequency during 1.0MHz to 1.4MHz is set by an external resistor and integrated soft-start (SS), under-voltage-lock-out (UVLO), thermal shutdown detection (TSD) and short circuit protection are designed to provide reliable product applications.

The device is available in adjustable output voltage versions ranging from 0.8V to V_{IN} when input voltage range is from 2.5V to 5.5V , and is able to deliver up to 2A.

The AUR9716 is available in DFN-3×3-8 package.

Features

- High efficiency Buck Power Converter
- Low Quiescent Current
- 2A Output Current
- Low $R_{DS(ON)}$ Internal Switches: 110mΩ
- Adjustable Output Voltage from 0.8V to V_{IN}
- Wide Operating Voltage Range: 2.5V to 5.5V
- Built-in Power Switches for Synchronous Rectification with high Efficiency
- 800mV Feedback Voltage Allows output
- Programmable Frequency: 1.0MHz to 1.4MHz
- Thermal Shutdown Protection
- Low Drop-out Operation at 100% Duty Cycle
- No Schottky Diode Required

Applications

- LCD TV
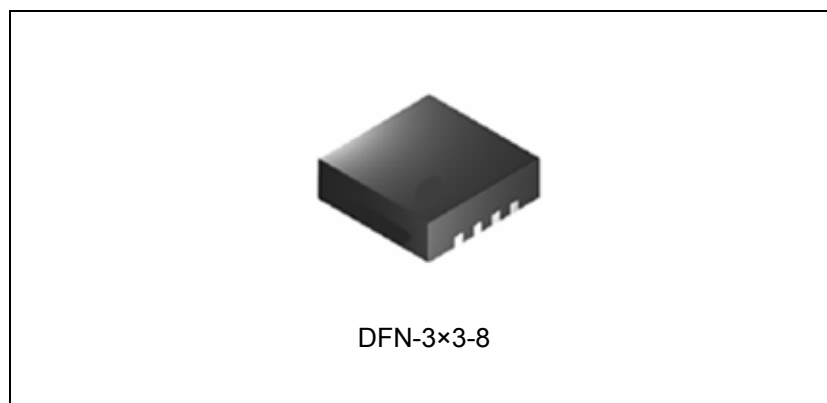- Post DC-DC Voltage Regulation
- PDA and Notebook Computers
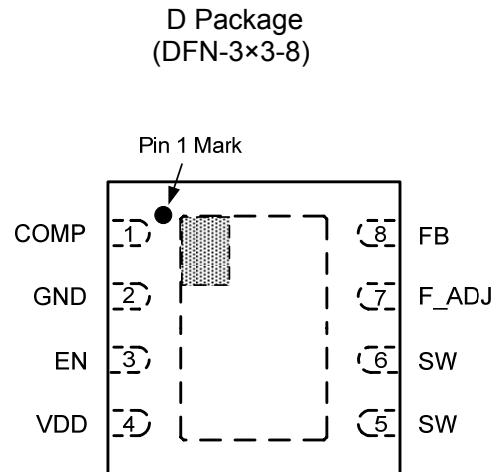

DFN-3×3-8

Figure 1. Package Type of AUR9716

1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716

Pin Configuration

D Package
(DFN-3×3-8)

Pin 1 Mark

COMP   1   8   FB

GND   2   7   F_ADJ

EN   3   6   SW

VDD   4   5   SW

Figure 2. Pin Configuration of AUR9716 (Top View)

Pin Description

Pin Number	Pin Name	Function
1	COMP	Compensation Point. COMP is used to compensate the regulation control loop. Connect R and C from COMP and GND to compensate the regulation control loop
2	GND	Ground. The exposed pad is soldered to PCB and connected to GND plant for good power dissipation
3	EN	Enable Input. EN is an input when the regulator on or off. When left unconnected, EN pin is pulled to VDD by the internal pull up resistor
4	VDD	Power input V_{IN} provides the input power to the regulator. Connecting a ceramic bypass capacitor between VDD and GND to eliminate input noise and ripple voltage
5	SW	Switch Output. SW is the switching point which supplies voltage and current to output
6		
7	F_ADJ	Oscillator Resistor Input. Connecting a resistor to ground from this pin sets the switching frequency
8	FB	Feedback Input. Receives the feedback voltage from a resistive divider connected across the output. The feedback reference voltage is 0.8V typically

1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716
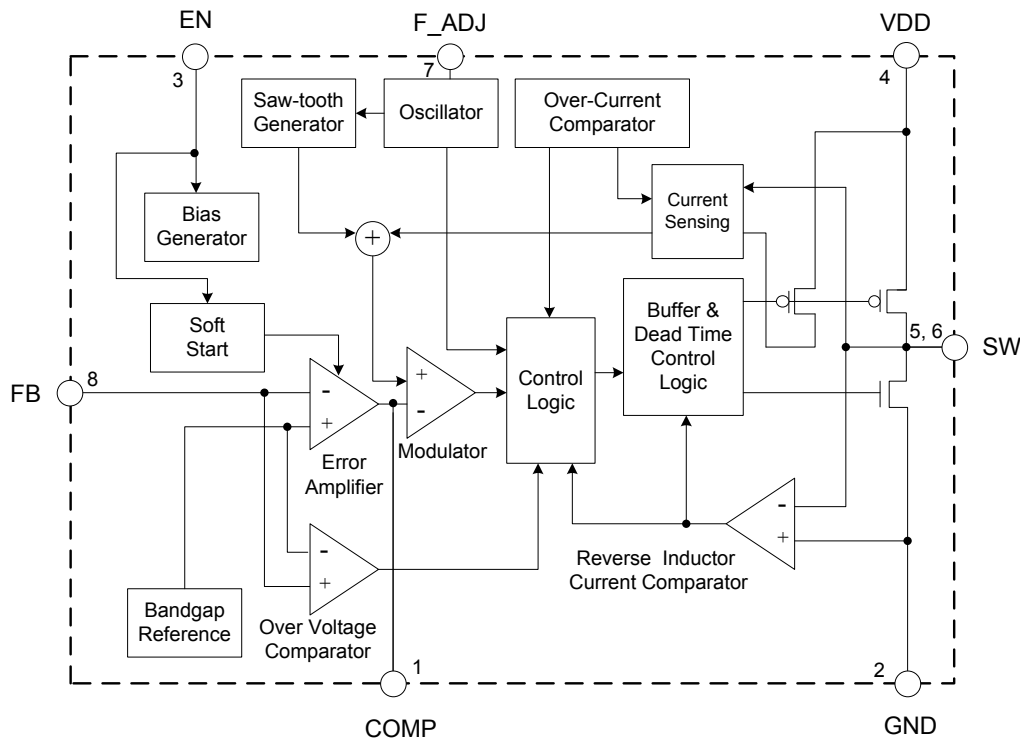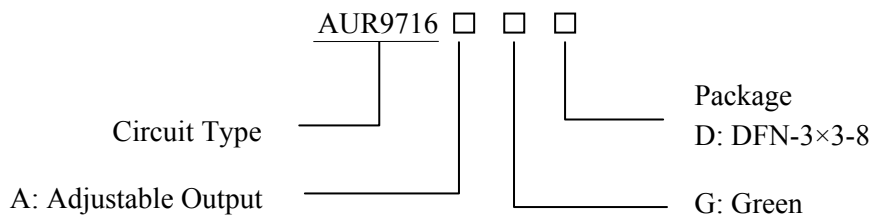
Functional Block Diagram

Figure 3. Functional Block Diagram of AUR9716

Ordering Information

AUR9716 ☐ ☐ ☐

Circuit Type

A: Adjustable Output

Package
D: DFN-3×3-8

G: Green

Package	Temperature Range	Part Number	Marking ID	Packing Type
DFN-3×3-8	-40 to 80°C	AUR9716AGD	9716A	Tape & Reel

BCD Semiconductor's Pb-free products, as designated with "G" in the part number, are RoHS compliant and green.

1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   **AUR9716**

Absolute Maximum Ratings (Note 1)

Parameter	Symbol	Value	Unit
Supply Input Voltage	V_{IN}	-0.3 to 6.0	V
SW Pin Switch Voltage	V_{SW}	-0.3 to V_{IN}+0.3	V
Output Voltage	V_{EN}	-0.3 to V_{IN} +0.3	V
P-MOSFET Switch Source Current	I_{SW-P}	3.5	A
N-MOSFET Switch Sink Current	I_{SW-N}	3.5	A
Power Dissipation (on PCB, T_A=25°C)	P_D	2.56	W
Package Thermal Resistance (Junction to Ambient)	θ_{JA}	39.13	°C/W
Package Thermal Resistance (Junction to Case)	θ_{JC}	3.39	°C/W
Lead Temperature (Soldering, 5sec)	T_{LEAD}	260	°C
Junction Temperature	T_J	150	°C
Operating Temperature Range	T_{OP}	-40 to 85	°C
Storage Temperature Range	T_{STG}	-55 to 150	°C
ESD (Human Body Model)	V_{HBM}	2000	V
ESD (Machine Model)	V_{MM}	200	V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Supply Input Voltage	V_{IN}	2.5	5.5	V
Junction Temperature Range	T_J	-20	125	°C
Operating Temperature Range	T_A	-40	80	°C

1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716

Electrical Characteristics

V_{IN}=5V, V_{FB}=0.8V, f_{OSC}=1.4MHz, L=1.5μH, C_{IN}=10μF, C_{OUT}=10μF, T_A=25°C, unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input Voltage Range	V_{IN}		2.5		5.5	V
Shutdown Current	I_{OFF}	V_{EN}=0V		0.1	1	μA
Active Current	I_{ON}	V_{FB}=0.95V		460		μA
Regulated Feedback Voltage	V_{FB}	For adjustable output voltage	0.784	0.8	0.816	V
Regulated Output Voltage	ΔV_{OUT} /V_{OUT}	V_{IN}=2.5V to 5.5V, I_{OUT}=0A to 2A	-3		3	%
Peak Inductor Current	I_{PK}	V_{FB}=0.7V	2.2	3.2	3.7	A
Oscillator Frequency	f_{OSC}	R_{OSC}=5.1MΩ	1.12	1.4	1.68	MHz
		Adjustable switching frequency	1.0		1.4	
P_MOSFET R_{ON}	$R_{DSON(P)}$	I_{SW}=0.5A	90	110	130	mΩ
N_MOSFET R_{ON}	$R_{DSON(N)}$	I_{SW}=0.5A	90	110	130	mΩ
EN Input High-Threshold Voltage	V_{ENH}	Enable Threshold	1.5			V
EN Input Low-Threshold Voltage	V_{ENL}	Shutdown Threshold			0.4	V
EN Input Current	I_{EN}			2		μA
Soft-start Time	t_{SS}			800		μs
Maximum Duty Cycle	D_{MAX}		100			%
Under Voltage Lock Out Threshold	V_{UVLO}	V_{IN} Rising		2.4		V
		V_{IN} Falling		2.3		
		Hysteresis		0.1		
Thermal Shutdown	T_{SD}	Hysteresis=30°C		150		°C
Error Amplifier Trans Conductance	g_m			3000		μs
Current Sense Trans Resistance	R_T			5		Ω

1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716
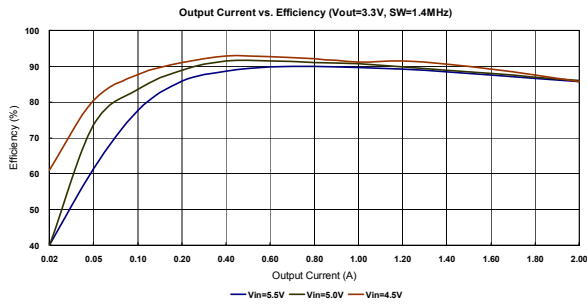
Typical Performance Characteristics

Figure 4. Output Current vs.Efficiency

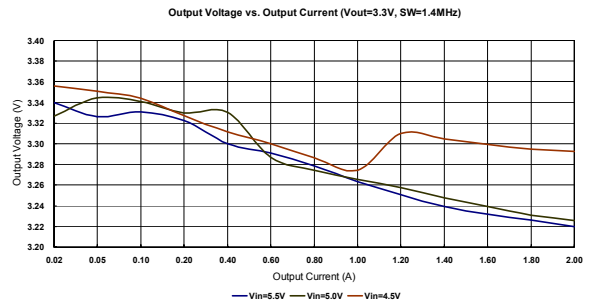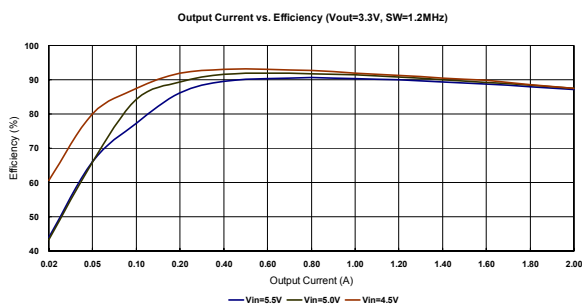Figure 5. Output Voltage vs. Output Current

Figure 6. Output Current vs.Efficiency

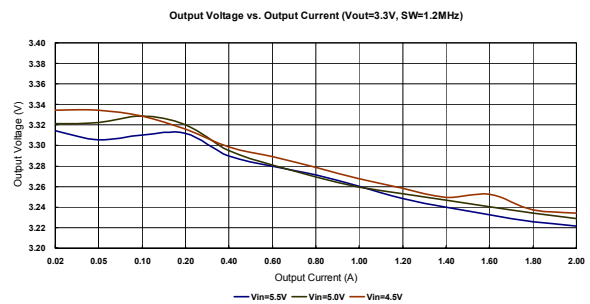Figure 7. Output Voltage vs. Output Current

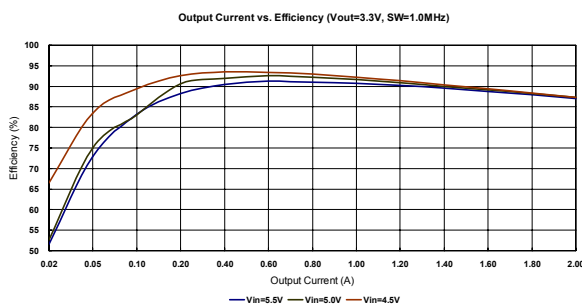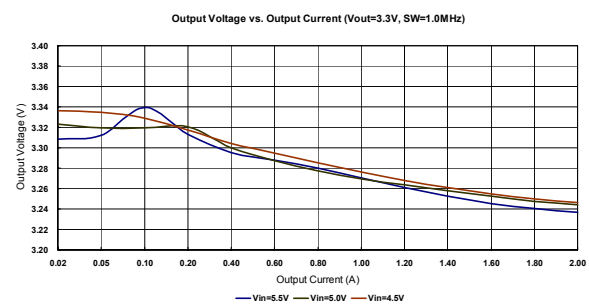Figure 8. Output Current vs.Efficiency

Figure 9. Output Voltage vs. Output Current

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1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716

Typical Performance Characteristics (Continued)
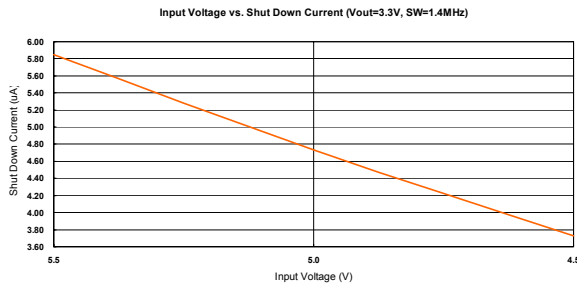
Figure 10. Input Voltage vs. Shutdown Current
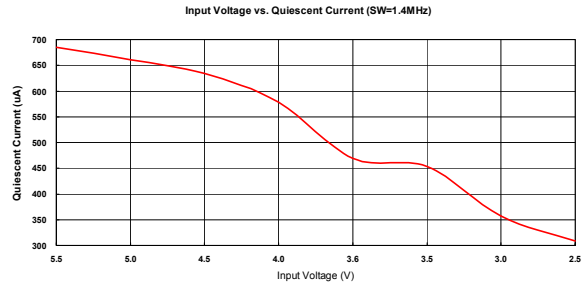
Figure 11. Input Voltage vs. Quiescent Current

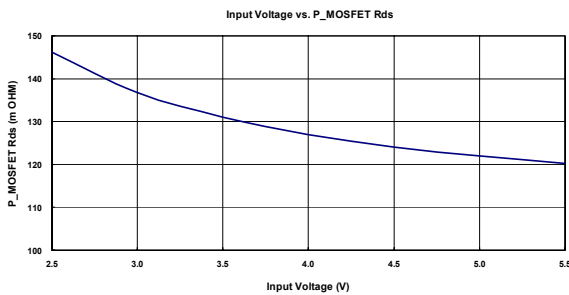
Figure 12. Input Voltage vs. P_MOSFET R_{DS}
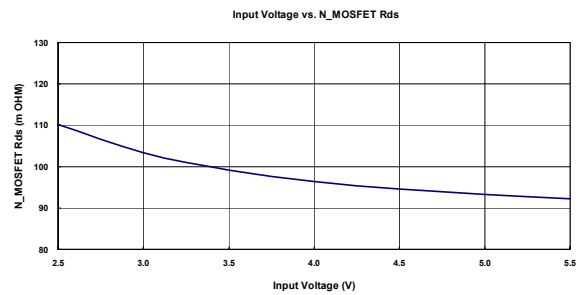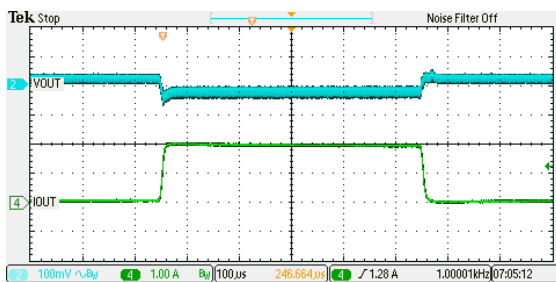

Figure 13. Input Voltage vs. N_MOSFET R_{DS}

Figure 14. Load Regulation (V_{IN}=5V, V_{OUT}=1.1V, f_{OSC}=1.4MHz, I_{OUT}=0.1A to 2A)
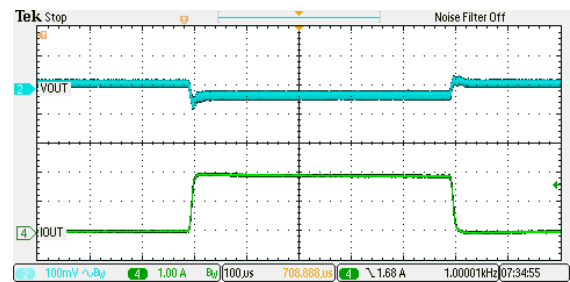

Figure 15. Load Regulation (V_{IN}=5V, V_{OUT}=1.1V, f_{OSC}=1.2MHz, I_{OUT}=0.1A to 2A)

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1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716

Typical Performance Characteristics (Continued)
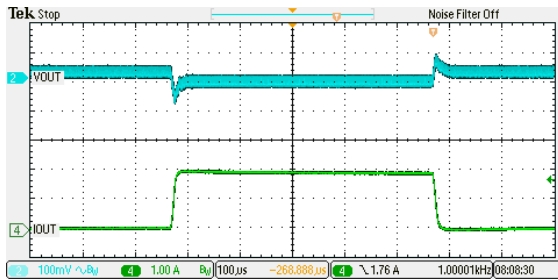

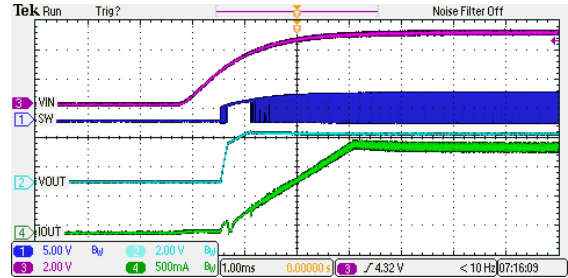Figure 16. Load Regulation (V_{IN}=5V, V_{OUT}=1.1V, f_{OSC}=1.0MHz, I_{OUT}=0.1A to 2A)

Figure 17. Power Start-up (V_{IN}=0V to 5V, V_{OUT}=3.3V, f_{OSC}=1.4MHz, I_{OUT}=2A)
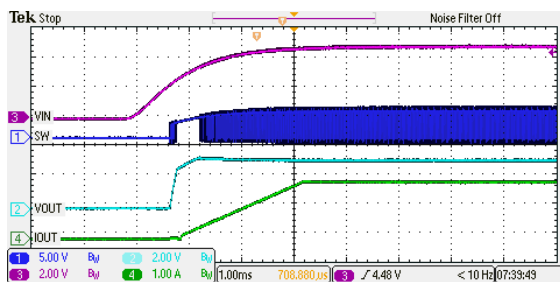

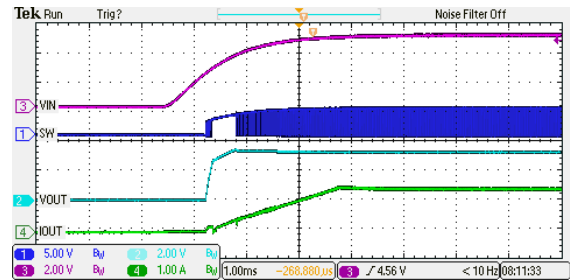Figure 18. Power Start-up (V_{IN}=0V to 5V, V_{OUT}=3.3V, f_{OSC}=1.2MHz, I_{OUT}=2A)

Figure 19. Power Start-up (V_{IN}=0V to 5V, V_{OUT}=3.3V, f_{OSC}=1.0MHz, I_{OUT}=2A)
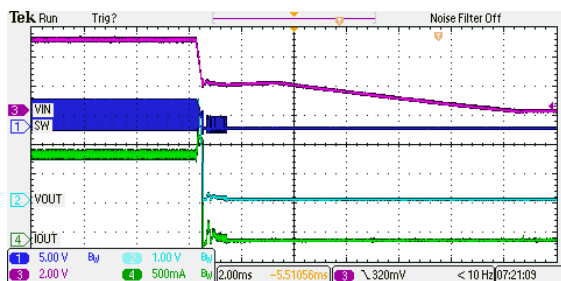

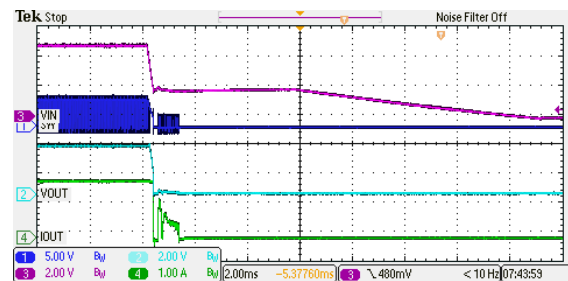Figure 20. Power Turn-off (V_{IN}=5V to 0V, V_{OUT}=3.3V, f_{OSC}=1.4MHz, I_{OUT}=2A)

Figure 21. Power Turn-off (V_{IN}=5V to 0V, V_{OUT}=3.3V, f_{OSC}=1.2MHz, I_{OUT}=2A)
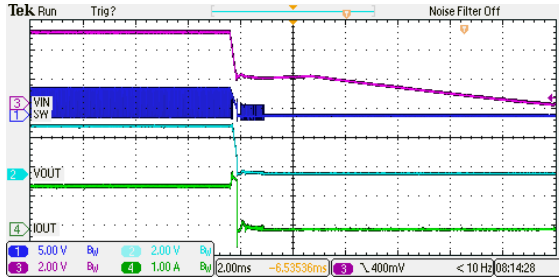
Typical Performance Characteristics (Continued)

Figure 22. Power Turn-off (V_{IN}=5V to 0V,
V_{OUT}=3.3V, f_{OSC}=1.0MHz, I_{OUT}=2A)

1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER   AUR9716

Application Information

The AUR9716 is a synchronous buck converter which can support switching frequency range from 1.0MHz to 1.4MHz and the output current can be up to 2A.

The basic AUR9716 application circuits are shown as Figure 27, external components selection is determined by the load current and is critical with the selection of inductor and capacitor values.

1. Inductor Selection

For most applications, the value of inductor is chosen based on the required ripple current with the range of 1.5μH to 4.7μH.

$$\Delta I_L = \frac{1}{f \times L} V_{OUT} (1 - \frac{V_{OUT}}{V_{IN}})$$

The largest ripple current occurs at the highest input voltage. Having a small ripple current reduces the ESR loss in the output capacitor and improves the efficiency. The highest efficiency is realized at low operating frequency with small ripple current. However, the larger value inductors will be required. A reasonable starting point for ripple current setting is $\Delta I_L = 40\% I_{MAX}$. For a maximum ripple current stays below a specified value, the inductor should be chosen according to the following equation:

$$L = [\frac{V_{OUT}}{f \times \Delta I_L (MAX)}][1 - \frac{V_{OUT}}{V_{IN}(MAX)}]$$

The DC current rating of the inductor should be at least equal to the maximum output current plus half of the highest ripple current to prevent inductor core saturation. For better efficiency, the lower DC-resistance inductor should be selected.

2. Capacitor Selection

The input capacitance, C_{IN}, is needed to filer the trapezoidal current at the source of the top MOSFET. To prevent the large ripple voltage, a low ESR input capacitor sized for the maximum RMS current must be used. The maximum RMS capacitor current is given by:

$$I_{RMS} = I_{OMAX} \times \frac{[V_{OUT}(V_{IN} - V_{OUT})]^{\frac{1}{2}}}{V_{IN}}$$

It indicates a maximum value at $V_{IN} = 2V_{OUT}$, where $I_{RMS} = \frac{I_{OUT}}{2}$. This simple worse-case condi-

tion is commonly used for design because even significant deviations do not much relief. The selection of C_{OUT} is determined by the equivalent series resistance (ESR) that is required to minimize output voltage ripple and load step transients, as well as the amount of bulk capacitor that is necessary to ensure the control loop is stable. Loop stability can be also checked by viewing the load step transient response as described in a latter section. The output ripple, ΔV_{OUT}, is determined by:

$$\Delta V_{OUT} \leq \Delta I_L [ESR + \frac{1}{8 \times f \times C_{OUT}}]$$

The output ripple is the highest at the maximum input voltage since ΔI_L increases with input voltage.

3. Load Transient

A switching regulator typically takes several cycles to respond to the load current step. When a load step occurs, V_{OUT} immediately shifts by an amount equal to $(\Delta I_{LOAD} \times ESR)$, where ESR is the equivalent series resistance of output capacitor. ΔI_{LOAD} also begins to charge or discharge C_{OUT} generating a feedback error signal used by the regulator to return V_{OUT} to its steady-state value. During the recovery time, V_{OUT} can be monitored for overshoot or ringing that would indicate a stability problem.

4. Output Voltage Setting

The output voltage of AUR9716 can be adjusted by a resistive divider according to the following formula:

$$V_{OUT} = V_{FB} \times (1 + \frac{R_1}{R_2}) = 0.8V \times (1 + \frac{R_1}{R_2})$$

When V_{FB} is the 0.8V feedback reference voltage, the resistive divider senses the fraction of the output voltage as shown in Figure 23.
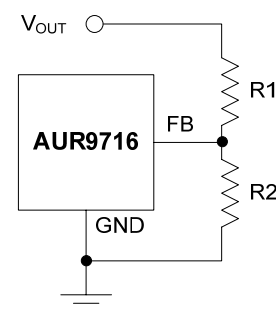

Figure 23. Setting the Output Voltage

Application Information (Continued)

5. Slope Compensation

The slope compensation of AUR9716 provides stability in constant frequency construction by preventing oscillations at duty cycle more than 50%. It's accomplished externally by adding a series of capacitor and resistor, as shown in Figure 24.
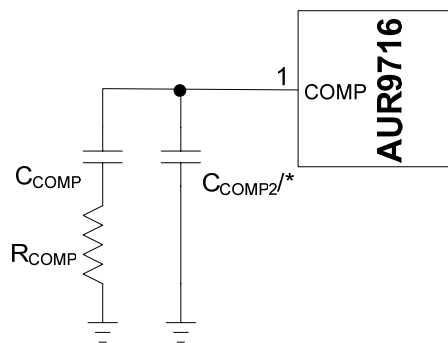

Figure 24. Stability Compensation Components

The DC loop gain of the system is determined by the following equation:

$$A_{VDC} = \frac{V_{FB}}{I_{OUT}} A_V G_{CS},$$

Where A_V is error amplifier voltage gain and G_{CS} is current sense transconductance.

The dominant pole P1 is due to C_{COMP}:

$$f_{P1} = \frac{G_{EA}}{2\pi A_V C_{COMP}},$$

Where G_{EA} is error amplifier transconductance.
The output pole P2 is due to C_{OUT}:

$$f_{P2} = \frac{I_{OUT}}{2\pi V_{OUT} C_{OUT}}$$

The zero Z1 is due to C_{COMP} and R_{COMP}:

$$f_{Z1} = \frac{1}{2\pi R_{COMP} C_{COMP}}$$

If C_{COMP2} is used, the third pole is due to R_{COMP} and C_{COMP2}:

$$f_{P3} = \frac{1}{2\pi R_{COMP} C_{COMP2}}$$

Then the cross over frequency often sets at 1/5 to 1/10 of the switching frequency.

Table 1 shows some calculated results based on stability compensation equations above.

Switching Frequency (MHz)	1.4	1.2	1.0
R_{COMP} (kΩ)	4.3	4.3	3.6
C_{COMP} (nF)	1	1	1.5
L (μH)	1.5	1.5	2.2
C_{OUT} (μF)	10	10	10

Table 1. Stability Compensation Components

To optimize the components for stability compensation listed in Table 1, we will introduce the selection value of R_{COMP} and C_{COMP} as detail as possible.

1. R_{COMP}: determine this resistor value according to the desired crossover frequency is f_C, default as 1.4MHz.

$$R_{COMP} = \frac{2\pi C_{OUT} f_C}{G_{EA} G_{CS}} \frac{V_{OUT}}{V_{FB}}$$

2. C_{COMP}: determine this capacitor value according to the desired phase margin. We often choose this compensation.

Zero point below one forth of the crossover frequency to ensure the loop stability.

$$C_{COMP} > \frac{4}{2\pi R_{COMP} f_C}$$

6. Short-Circuit Protection

When AUR9716 output node is shorted to GND, as V_{FB} drops under 0.4V, chip will enter soft-start to protect itself, when short circuit is removed, and V_{FB} rises over 0.4V, the AUR9716 enters normal operation again. If AUR9716 reaches OCP threshold while short circuit, it will enter soft-start cycle until the current under OCP threshold. When AUR9716 is used to transfer V_{IN}=5V to V_{OUT}=2.5V, shorting V_{OUT} to GND makes big current which enables SCP protection. The waveform is shown in Figure 25.

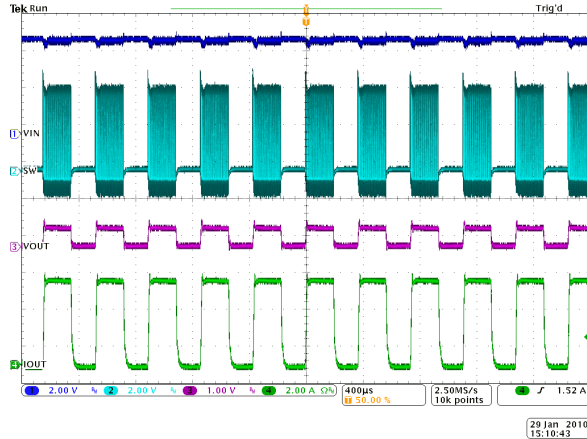## Application Information (Continued)

Figure 25. SCP Protection

7. F_ADJ : R$_{OSC}$ Selection

The AUR9716 can change switching frequency by choose different R$_{OSC}$, please refer to Table 2.

Switching Frequency (MHz)	1.4	1.2	1.0
R$_{OSC}$ (kΩ)	5100	976	536

Table 2. R$_{OSC}$ Setting

Due to get the better performance of AUR9716, F_ADJ pin （Pin 7）could parallel 47pF capacitor with R$_{OSC}$, shown in Figure 26.
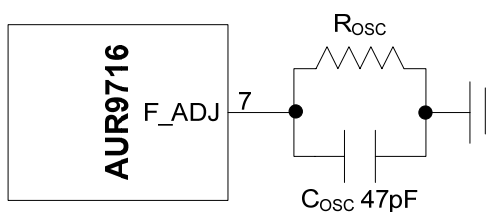

Figure 26. F_ADJ Components

8. Thermal Characteristics

The max power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of temperature between junction to ambient. The max power dissipation can be calculated by following formula:

$$P_{D(MAX)} = \left(\frac{T_{J(MAX)} - T_A}{\theta_{JA}} \right)$$

Where T$_{J(max)}$ is the maximum operation junction temperature, T$_A$ is the ambient temperature and θ$_{JA}$ is the junction to ambient thermal resistance.

9. PC Board Layout Considerations

When laying out the printed circuit board, the following checklist should be used to optimize the performance of AUR9716.

1. The power traces, including the GND trace, the SW trace and the VDD trace should be kept direct, short and wide.

2. To put the input capacitor as close as possible to the VDD and GND pins.

3. The FB pin should be connected directly to the feedback resistor divider.

4. Keep the switching node, SW, away from the sensitive FB pin and the node should be kept small area.
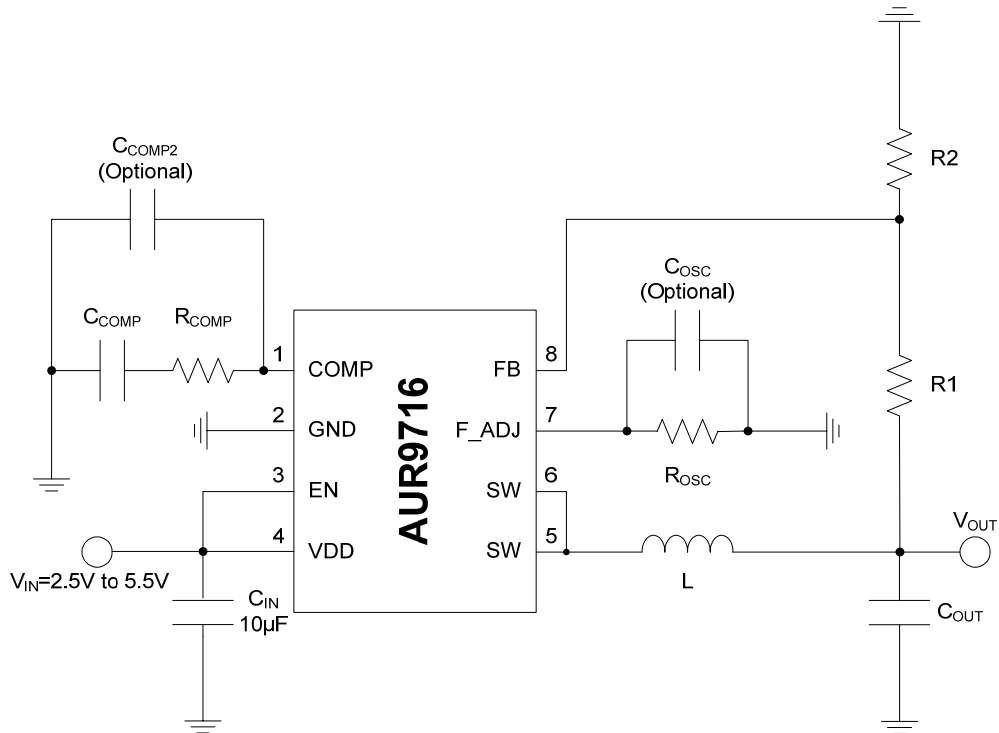

Typical Application

Figure 27. Typical Application Circuit of AUR9716
(Switching Frequency=1.0MHz to 1.4MHz)

V_{OUT} (V)	R1 (kΩ)	R2 (kΩ)
3.3	6.25	2
2.5	4.25	2
1.8	2.5	2
1.1	0.75	2

Switching Frequency (MHz)	R_{OSC} (kΩ)	R_{COMP} (kΩ)	C_{COMP} (nF)	L (μH)	C_{OUT} (μF)
1.0	536	3.6	1.5	2.2	10
1.2	976	4.3	1.0	1.5	10
1.4	5100	4.3	1.0	1.5	10

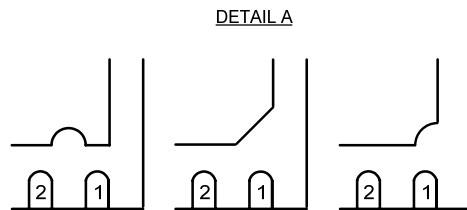Apr. 2012   Rev. 1. 0   BCD Semiconductor Manufacturing Limited

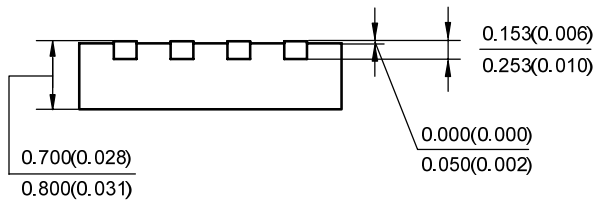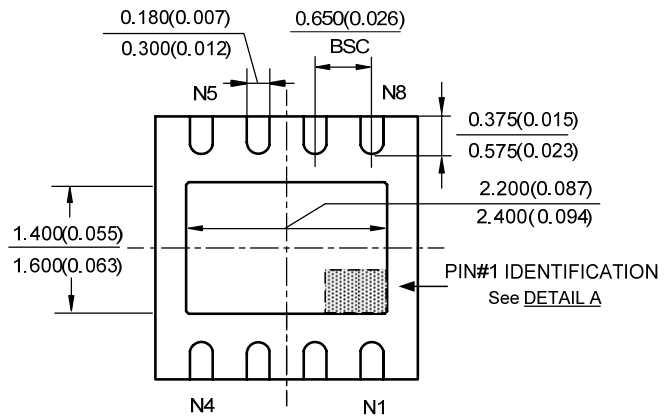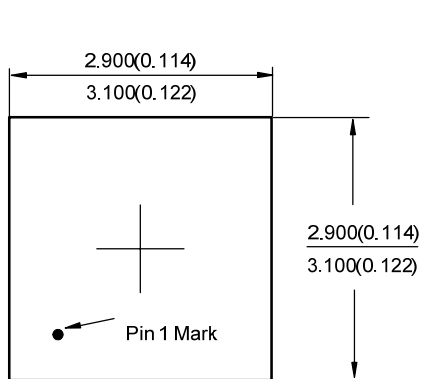**1.0MHz to 1.4MHz, 2A, STEP DOWN DC-DC CONVERTER**   **AUR9716**

Mechanical Dimensions

DFN-3×3-8   **Unit:mm(inch)**

DETAIL A

Pin 1 options

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